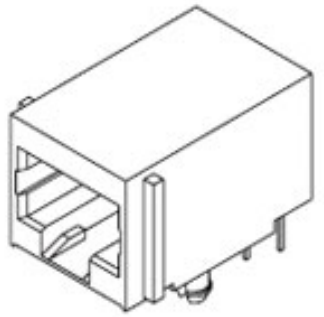
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PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0432496107
Status: Active
Overview: modular_plugs_jacks
Description: Modular Jack, Right Angle, Low Profile, 6/2, Flangeless



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Product Specification PSX-43249 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E107635

General

Product Family	Modular Jacks/Plugs
Series	43249
Component Type	PCB Jack
Magnetic	No
Overview	modular_plugs_jacks
Performance Category	3
Power over Ethernet (PoE)	N/A
Product Name	RJ11

Physical

Boot Color	N/A
Color - Resin	Black
Durability (mating cycles max)	500
Flammability	94V-0
Inverted / Top Latch	No
Lightpipes/LEDs	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Orientation	Right Angle (Side Entry)
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.57 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.040 In
Pitch - Mating Interface (mm)	1.02 mm
Pitch - Term. Interface (in)	0.050 In
Pitch - Term. Interface (mm)	1.27 mm
Plating min: Mating (µin)	50
Plating min: Mating (µm)	1.25
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Ports	1
Positions / Loaded Contacts	6/2
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole
Waterproof / Dustproof	No
Wire/Cable Type	N/A

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
43249Series

Mates With
FCC 68 Plugs

Electrical

Current - Maximum per Contact	1.5A
Grounding to Panel	N/A
Shielded	No
Voltage - Maximum	150V AC (RMS)

Solder Process Data

Lead-free Process Capability	Wave Capable (TH only)

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-43249-004
Product Specification	PSX-43249
Sales Drawing	SDA-43249

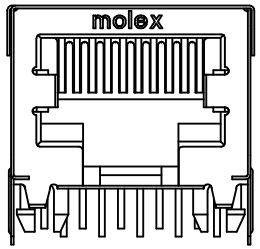
This document was generated on 06/07/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

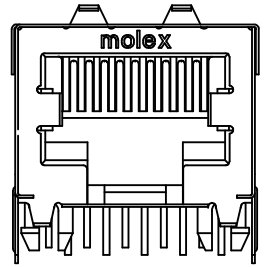
NOTES:

1) MATERIAL:
   HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
   INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
   TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
   SHIELD: BRASS, .007/(0.18) THICK
2) FINISH:
   TERMINALS:
   A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
   *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
   WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
   B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
   *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
   WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
   SHIELD:
   *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27 MICROMETERS COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
   *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.
4) PACKAGING SPECIFICATION:
   UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
   UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
   SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44050-004.
5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.
6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.
8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.
10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

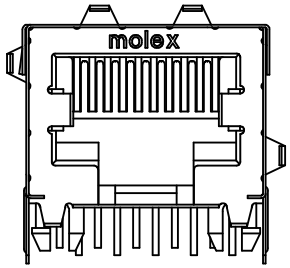
SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



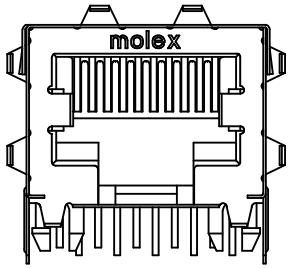
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

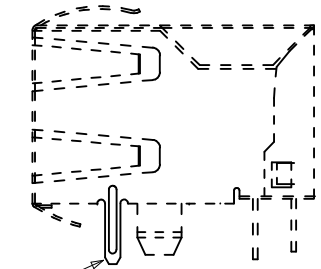


OPTION "C"
TOP AND STAGGERED SIDE TABS

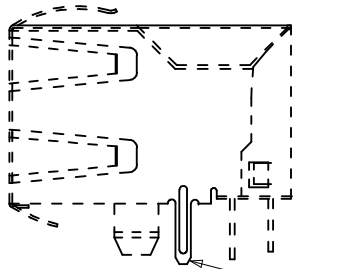


OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE ON ALL SIDE/TOP TAB CONFIGURATIONS

DRAWING LEGEND

SHEET 1- NOTES; GROUND TAB OPTIONS
SHEET 2- UNSHIELDED MODULAR JACK
SHEET 3- SHIELDED MODULAR JACK WITH OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND TAB WITH OPTIONAL POSITION.
SHEET 4- PART NUMBER CHARTS
SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

REV	DESCRIPTION	
K1	ADDED NOTE 10	EC NO: UCP2009-0740 DRWN:JKLOSTEMEIER 2008/09/29 CHKD:JBELL 2008/10/03 APPR:FSMITH 2008/10/03

QUALITY SYMBOLS
▼=0
▽(C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY	JTR	DATE 1993/06/23
CHECKED BY	JTR	DATE 1993/06/23
APPROVED BY	RAS	DATE 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

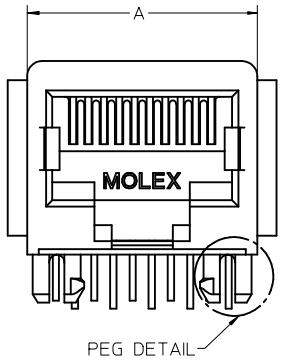
MOLEX INCORPORATED

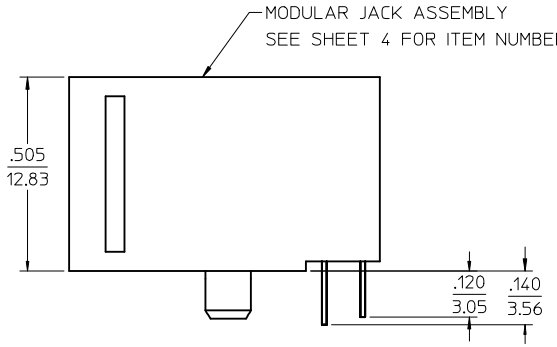
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 1 OF 6
SIZE: C

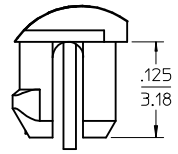
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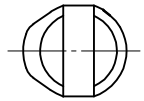
UNSHIELDED MODULAR JACK

8 POSITION LOADED 10 SIZE SHOWN

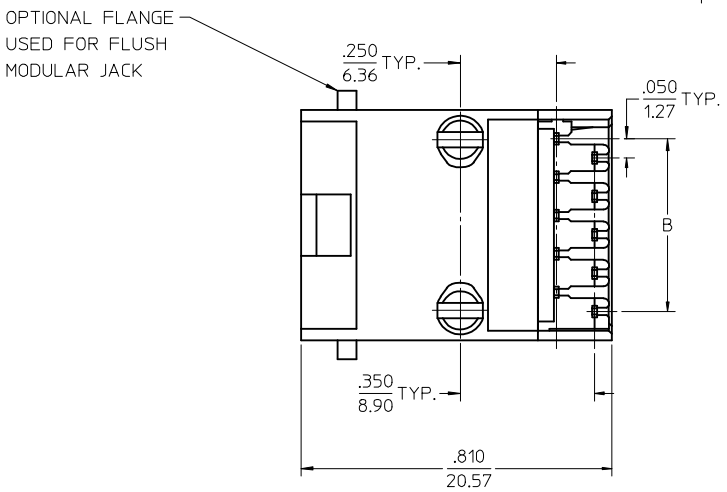


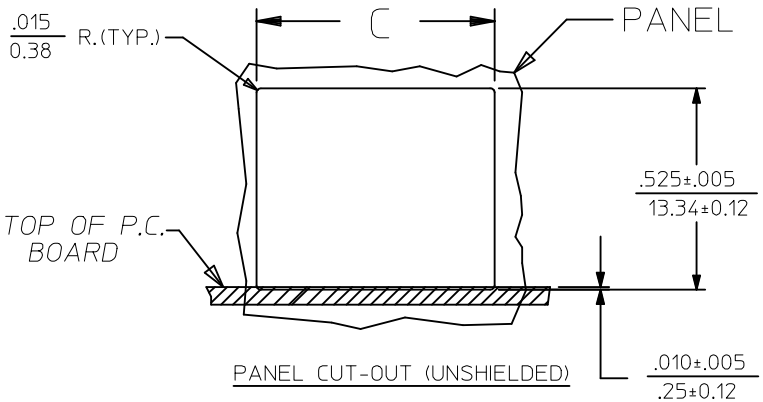






PEG DETAIL
SCALE 8:1





HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CHKD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: JTR DATE: 1993/06/23
CHECKED BY: JTR DATE: 1993/06/23
APPROVED BY: RAS DATE: 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

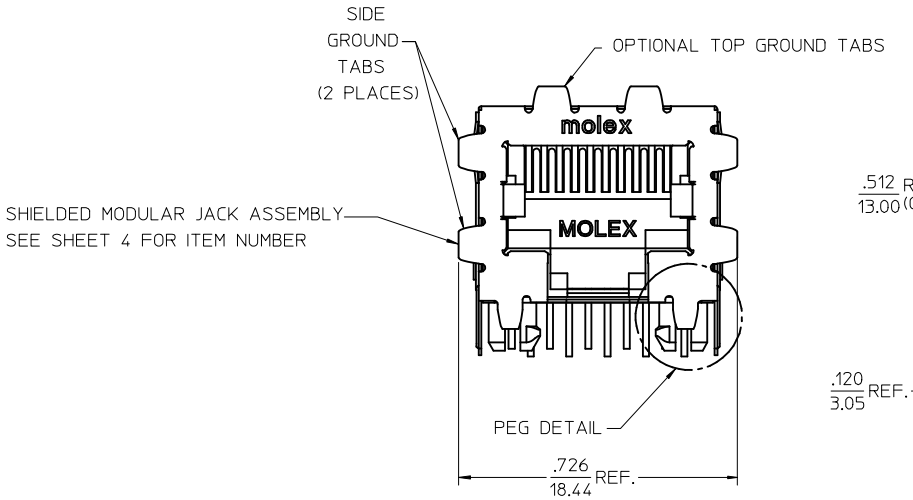
MOLEX INCORPORATED

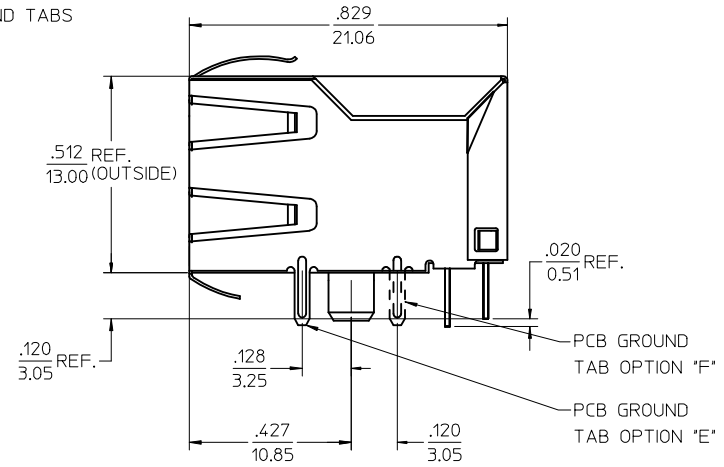
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 2 OF 6
SIZE: C

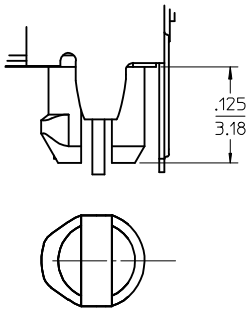
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MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

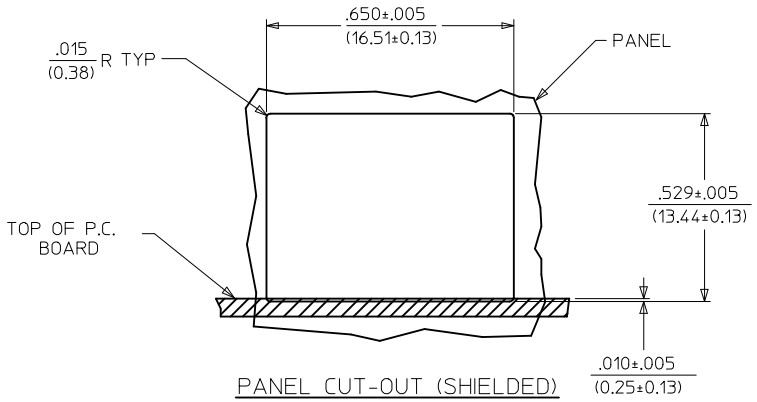
8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



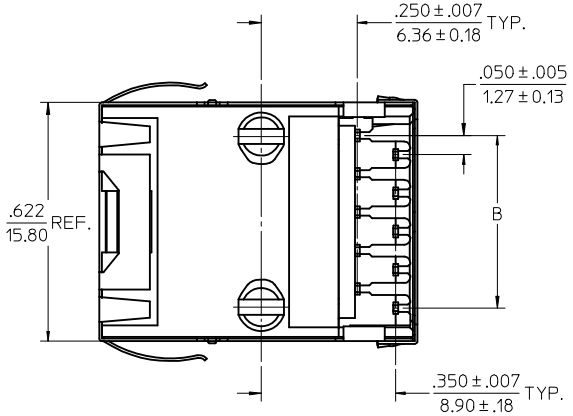




PEG DETAIL
SCALE 8:1



PANEL CUT-OUT (SHIELDED)



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450±.005 / 11.43±0.13
8	8	.350±.005 / 8.89±0.13

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CHKD: JBELL 2008/10/03
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JTR	1993/06/23
CHECKED BY	JTR	1993/06/23
APPROVED BY	RAS	1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 3 OF 6

SIZE C

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FLUSH MOUNT (UNSHIELDED)

ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
43249-8001	8	10	A
43249-8004	8	8	A
43249-8010	8	6	A
43249-6001	6	6	A
43249-6004	6	4	A
43249-6007	6	2	A

FLANGELESS (UNSHIELDED)

ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
43249-8101	8	10	A
43249-8102	8	10	B
43249-8104	8	8	A
43249-8105	8	8	B
43249-8116	8	6	A
43249-8119	8	4	A
43249-6101	6	6	A
43249-6104	6	4	A
43249-6107	6	2	A

FLANGELESS (UNSHIELDED)
(SHIPPED IN TUBES)

43249-6501	6	6	A
43249-6504	6	4	A

SHIELDED, .007" THICK

ASSEMBLY ITEM NUMBER	CONN. SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	PACKAGING OPTION
43249-8900	8	10	A	A	E	TRAY
43249-8901	8	10	A	B	E	TRAY
43249-8902	8	10	A	C	E	TRAY
43249-8903	8	10	A	D	E	TRAY
43249-8908	8	10	A	A	F	TRAY
43249-8909	8	10	A	B	F	TRAY
43249-8910	8	10	A	C	F	TRAY
43249-8911	8	10	A	D	F	TRAY
43249-8916	8	8	A	A	E	TRAY
43249-8917	8	8	A	B	E	TRAY
43249-8918	8	8	A	C	E	TRAY
43249-8919	8	8	A	D	E	TRAY
43249-8920	8	8	B	A	E	TRAY
43249-8924	8	8	A	A	F	TRAY
43249-8925	8	8	A	B	F	TRAY
43249-8926	8	8	A	C	F	TRAY
43249-8927	8	8	A	D	F	TRAY

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTERMEIER 2008/10/03
CH'KD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: JTR DATE: 1993/06/23
CHECKED BY: JTR DATE: 1993/06/23
APPROVED BY: RAS DATE: 1993/06/23

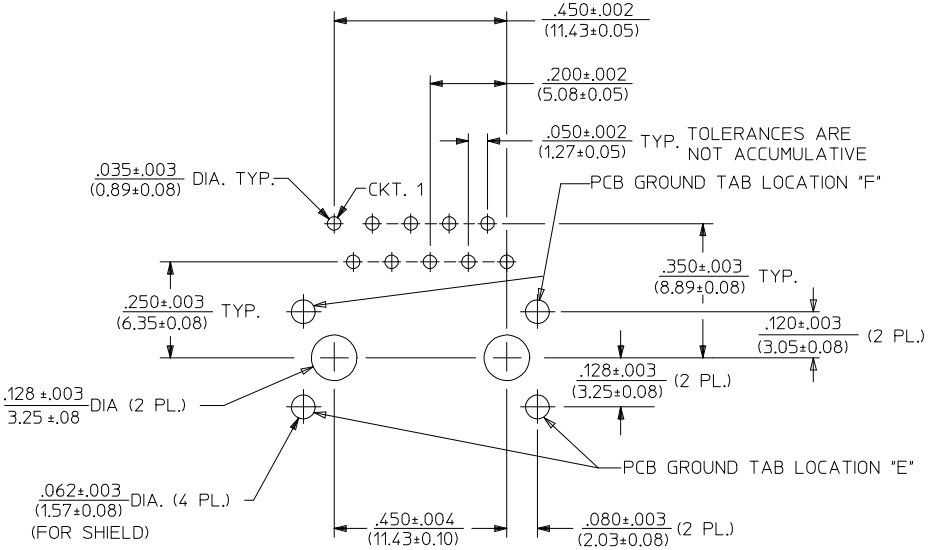
TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

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MATERIAL NO.: SEE CHART
DOCUMENT NO.: SDA-43249
SHEET NO.: 4 OF 6

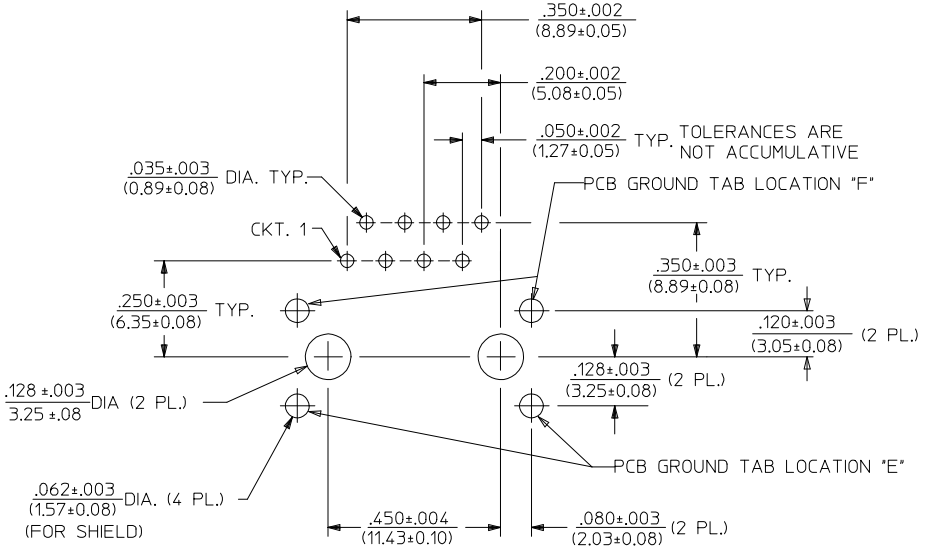
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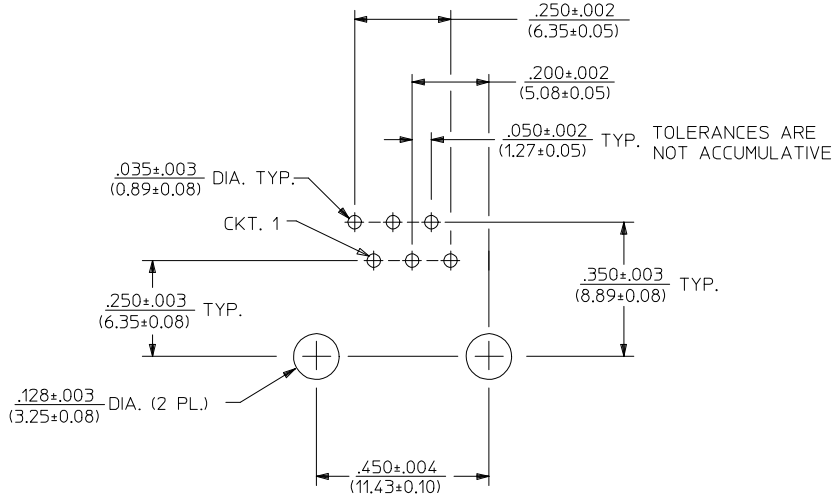
PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CH'KD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
REV
K1

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

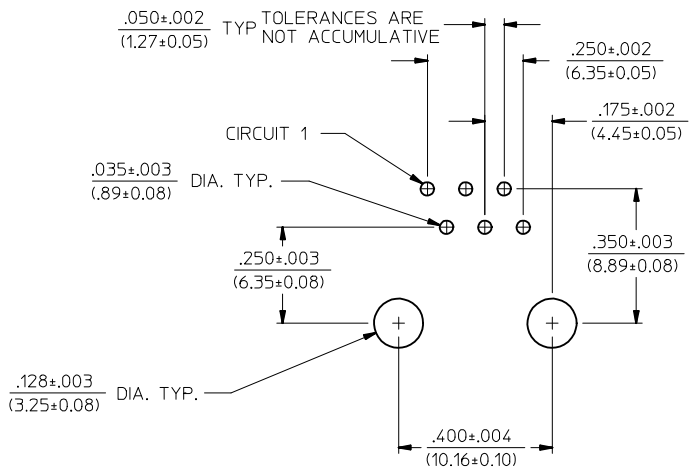
DRAWN BY	JTR	DATE 1993/06/23
CHECKED BY	JTR	DATE 1993/06/23
APPROVED BY	RAS	DATE 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

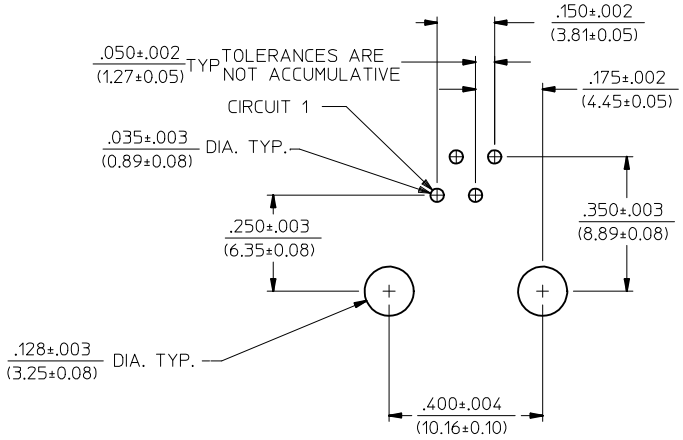
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 5 OF 6
SIZE: C

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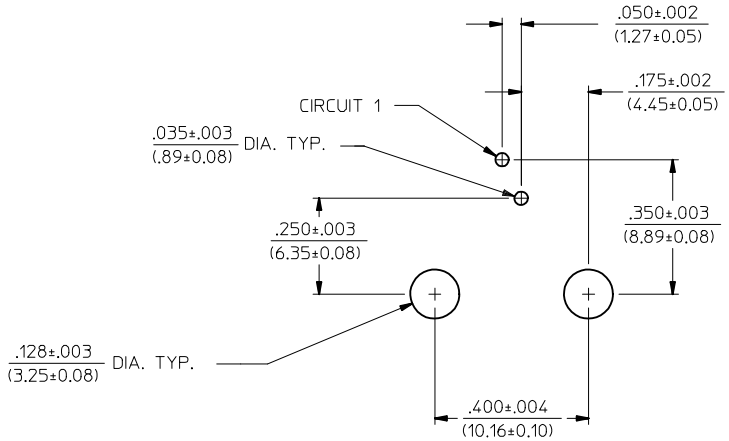
PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CH'KD: JBELL
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY	JTR	DATE 1993/06/23
CHECKED BY	JTR	DATE 1993/06/23
APPROVED BY	RAS	DATE 1993/06/23

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